

WHAT IS CLAIMED IS:

1. A semiconductor package, comprising:
 - a die pad defining opposed top and bottom surfaces and a peripheral edge;
 - a plurality of support feet attached to the peripheral edge of the die pad and extending downwardly relative to the bottom surface thereof;
 - a plurality of leads extending at least partially about the peripheral edge of the die pad in spaced relation thereto;
 - a semiconductor die attached to the top surface of the die pad and electrically connected to at least one of the leads; and
 - a package body encapsulating the die pad, the support feet, the leads and the semiconductor die such that at least portions of the leads are exposed in the package body.
2. The semiconductor package of Claim 1 wherein the support feet extend generally perpendicularly relative to the bottom surface of the die pad.
3. The semiconductor package of Claim 1 wherein each of the support feet defines a pointed distal end.
4. The semiconductor package of Claim 1 wherein:
 - each of the leads defines an inner lead portion which is covered by the package body and an outer lead portion which protrudes from the package body;
 - the die pad and the inner lead portions of the leads extend in generally co-planar relation to each other along a common die pad plane; and
 - the outer lead portions of the leads extend in generally co-planar relation to each other along a common lead plane which is disposed in spaced, generally parallel relation to the die pad plane.
5. The semiconductor package of Claim 1 wherein:
 - the die pad has a generally rectangular configuration defining an opposed pair of longitudinal sides and an opposed pair of lateral sides; and
 - the support feet are attached to each of the longitudinal and lateral sides of the die pad.
6. The semiconductor package of Claim 1 wherein:

the die pad has a generally quadrangular configuration defining four corner regions; and

the support feet are attached to respective ones of the corner regions defined by the die pad.

7. The semiconductor package of Claim 1 further comprising:

a pair of inner support bars attached to and extending from the peripheral edge of the die pad, the inner support bars being at least partially covered by the package body.

8. The semiconductor package of Claim 1 wherein the semiconductor die is electrically connected to at least one of the leads via a conductive wire.

9. A leadframe for use in a semiconductor package, the leadframe comprising:

a die pad defining opposed top and bottom surfaces and a peripheral edge;

a plurality of support feet attached to the peripheral edge of the die pad and extending generally perpendicularly therefrom;

a plurality of leads extending at least partially about the peripheral edge of the die pad in spaced relation thereto;

at least one outer support bar attached to and extending between the leads in a manner interconnecting the leads to each other; and

a pair of inner support bars attached to and extending between the outer support bar and the peripheral edge of the die pad.

10. The leadframe of Claim 9 wherein:

each of the leads includes an inner lead portion and an outer lead portion, the outer support bar being attached to and extending between the outer lead portions of the leads; and

each of the leads and each of the inner support bars includes a downset therein such that the die pad and the inner lead portions extend in generally co-planar relation to each other along a common die pad plane and the outer lead portions and the outer support bar extend in generally co-planar relation to each other along a common lead plane which is disposed in spaced, generally parallel relation to the die pad plane.

11. The leadframe of Claim 9 wherein each of the support feet defines a pointed distal end.

12. The leadframe of Claim 9 wherein:

the die pad has a generally rectangular configuration defining an opposed pair of longitudinal sides and an opposed pair of lateral sides; and

the support feet are attached to each of the longitudinal and lateral sides of the die pad.

13. The leadframe of Claim 9 wherein:

the die pad has a generally quadrangular configuration defining four corner regions; and

the support feet are attached to respective ones of the corner regions defined by the die pad.

14. A semiconductor package, comprising:

a die pad including a plurality of peripheral frame segments which each define opposed top and bottom surfaces and collectively define a central opening;

a plurality of support feet attached to at least some of the frame segments of the die pad, the support feet being disposed within the central opening and extending downwardly relative to the bottom surfaces of the frame segments;

a plurality of leads extending at least partially about the die pad in spaced relation thereto;

a semiconductor die attached to the top surfaces of at least some of the frame segments of the die pad and electrically connected to at least one of the leads; and

a package body encapsulating the die pad, the support feet, the leads and the semiconductor die such that at least portions of the leads are exposed in the package body.

15. The semiconductor package of Claim 14 wherein the support feet extend generally perpendicularly relative to the bottom surfaces of the frame segments of the die pad.

16. The semiconductor package of Claim 14 wherein each of the support feet defines a pointed distal end.

17. The semiconductor package of Claim 14 wherein:

each of the leads defines an inner lead portion which is covered by the package body and an outer lead portion which protrudes from the package body;

the die pad and the inner lead portions of the leads extend in generally co-planar relation to each other along a common die pad plane; and

the outer lead portions of the leads extend in generally co-planar relation to each other along a common lead plane which is disposed in spaced, generally parallel relation to the die pad plane.

18. The semiconductor package of Claim 14 wherein:

the die pad has a generally rectangular configuration defining an opposed pair of longitudinal frame segments and an opposed pair of lateral frame segments; and

the support feet are attached to each of the longitudinal and lateral frame segments of the die pad.

19. The semiconductor package of Claim 14 further comprising:

a pair of inner support bars attached to and extending from at least two of the frame segments of the die pad, the inner support bars being at least partially covered by the package body.

20. The semiconductor package of Claim 14 wherein the semiconductor die is electrically connected to at least one of the leads via a conductive wire.